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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. MAEJIMA, et al.

Serial No: 09/704,529

Filed: November 3, 2000

Title: WAFER HAVING CHAMFERED BEND PORTIONS IN THE  
JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER  
AND THE CUT-AWAY PORTION OF THE WAFER

Group: 2814

Examiner: L. PHAM

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

March 7, 2005

Sir:

In response to the Office Action dated September 9, 2004, please  
amend the above-identified application as listed below and as set forth on the  
following pages:

Amendments to the Claims

Remarks are included following the amendments